



Type Document	Product Specification	Revised /Edition	D
Date Issued	2010/03/19	Data Revised	2013/12/06
Subject: JS-11801SFTD 2.00mm SIP Socket			Issued By: Engineering Dept.

This specification is referred to the SIP Socket
 本規格書內容係提供 SIP 插座 2.00 mm 系列產品相關參考，

-INDEX-

- 1.0 Product Name/Part Number & Drawing Number.
(產品名稱 / 產品型號及圖面型號)
- 2.0 Construction/Dimensions/Material & Surface Finish.
(材質以及表面鍍層)
- 3.0 Characteristic.
(產品特性)
- 4.0 Specimen.
(樣本圖示)
- 5.0 Applicable Standards.
(適用規範)
- 6.0 Mechanical Performance.
(機械性能)
- 7.0 Electrical Performance.
(電氣性能)
- 8.0 Environmental Performance.
(環境性能)
- 9.0 Remark(備註).

REV. (版本)	Revision Record (改版變更原因)	Date(日期)	EC No
B	增加漏電流小於0.5mA偵測值	2011/05/30	EC2011-05-089
C	1原電氣性能Rated Current 1A AC/ DC修改3A AC/ DC 2增列Rated Voltage: 60 V AC/DC 3 刪除硫化氫 4 修正(EIA-364) 參考規範 5 耐久性 100Cycle 修訂為 200 6Contact Retention Force in Base 修訂為 1.0 kgf/Min. 7 Mating Force 修訂為 0.05kgf/Max. 8 Unating Force 修訂為 0.015kgf/Min.	2013/04/09	EC2013-04-009
D	1 增訂Wave Peak Soldering In- Process Temperature Profile 2.修訂Solder Ability 附註Tin Plated : 95% / Gold Plated : 75%	2013/12/06	EC2013/12/006



喬訊電子工業股份有限公司
CHYAO SHIUNN ELECTRONIC INDUSTRIAL LTD.

7FL., NO.17, LANE 3, SEC.1 CHUNG CHENG EAST RD.,
TAMSHUI, TAIPEI, TAIWAN, R.O.C.
TEL: 886-2-2629-9955 (REP) FAX: 886-2-2626-6677



http://www.chyaoshiunn.com.tw E-mail:cs@chyaoshiunn.com.tw

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1.0 Product Name/Part Number & Drawing Number (產品名稱 / 產品型號及圖面型號) :

Product Name(產品名稱)	Part Number(產品型號)	Drawing Number(圖面型號)
SIP Socket	JS-11801SFTD	JS-11801SFTD-XX

Note: (XX) The number of the circuits.

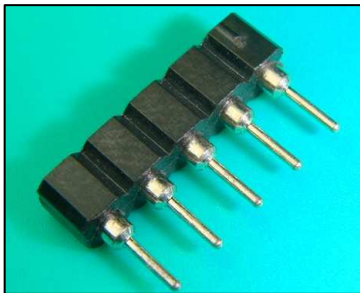
2.0 Construction/Dimensions/Material & Surface Finish (材質以及表面鍍層):

Part Name(零件名稱)		Material(材質)	Surface Finish(表面鍍層)
SIP Socket	Contacts (導體)	Beau 內襯 Sleeve Barrel 外套筒	Beryllium Copper 鈹銅合金 Brass
	Base(膠座)	PPS	Gold-Plated Tin-Plated
			UL 94V-0

3.0 Characteristic (產品特性):

Item(項目)	Standard(標準規範)
3.1 額定電流 Rated Current	3 A
3.2 額定電壓 Rated Voltage	60 V AC/DC
3.3 Ambient Temperature Range 環境與操作溫度範圍	(操作使用溫度範圍) Operating Temp. : -40°C~+105°C (置存於環境當中溫度與濕度範圍) Non – Operating Temp. : -40°C~+105°C ; 90% R.H
3.4 Applicable Printed Circuit Board Layout 適用電路板佈局設計	3.4.1 (電路板厚度) Thickness: 0.8~1.6 mm 3.4.2 Pitch Layout(孔與孔間距離) : 2.00±0.05mm 3.4.3 Pin Layout(導體孔外徑) : 0.80±0.05mm

4.0 Specimen(樣本圖示) :

Part Name / Part Number / Picture or Photograph	零件名稱 / 零件型號 / 樣本圖示
SIP Socket Single Row JS-11801SFTD	



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5.0 Applicable Standards(適用規範):

ANSI/EIA 364 ; EIA/ECA 364 Testing method for electrical connectors.

電子連接器，所適用之 ANSI/EIA 364 ; EIA/ECA 364 測試規範

6.0 Mechanical Performance(機械性能):

Item(項目)	Test Condition(測試條件)	Requirement(規格)
6.1 Mating Force (With 0.46 Diameter test pin) 測試用圓 Pin 針 與插座之間 嵌入力	Insertion with connectors at the speed rate of 25.4± 3mm/minute. (EIA/ECA 364-13D) 測試用 Pin 針與插座之間，施以每一分鐘 25.4 ± 3 mm 速 率之軸向嵌入力	單一接觸點 最大容許值 Per Contact 0.05kgf/Max.
6.2 Unmating Force (With 0.46 Diameter test pin) 測試用圓 Pin 針 與插座之間拔出力	Withdrawal with connectors at the speed rate of 25.4± 3mm/minute. (EIA/ECA 364-13D) 測試用 Pin 針與插座之間，施以每一分鐘 25.4 ± 3 mm 速 率之軸向拔出力	單一接觸點 最小容許值 Per Contact 0.015kgf/Min.
6.3 Contact Retention Force in Base 金屬導體與膠座之間拔出力	Axial pullout force on the pin in the base at the speed rate of 25.4 ± 3 mm per minute. (EIA/ECA 364-29C) 對於已經存在於膠座當中金屬導體，施以每一分鐘 25.4 ± 3 mm 速率之軸向拔出力	單一接觸點 最小容許值 Per Contact 1.0 kgf/Min.
6.4 Durability 耐久性	Connector shall be subject to 200 cycles of insertion and withdrawal. (with 0.46 Diameter test pin) 測試用圓Pin針與插座之間，連續200次 嵌入與拔出往返測試 (EIA/ECA 364-09C)	Contact resistance : 經耐久性試驗後接觸阻抗 : 20 mΩ Max



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7.0 Electrical Performance(電氣性能) :

Item(項目)	Test Condition(測試條件)	Requirement(規格)
7.1 Contact Resistance (低階信號) 接觸阻抗	A maximum voltage of 20mV and a maximum current of 100mA are applied to the mate connector. 以測試用 Pin 針與插座嵌合, 於其兩端施以最大電壓 20mV 以及最大電流 100mA (EIA/ECA 364-23C)	Contact Resistance: 10 milliohms Max. 最大容許值. 10m 歐姆
7.2 Insulation Resistance 絕緣阻抗	Apply 500V D/C to any two adjacent contacts to measure the insulation resistance. 對相鄰兩接觸導體, 各施以 500V D/C 電壓以量測其間絕緣阻抗值 (EIA 364-21C)	Insulation Resistance: Initial 1000megohms Min 最初容許值. 1000M 歐姆
7.3 Withstanding Voltage 耐電壓	Apply 1000V A/C (rms) for 1 minute and the leakage current shall not exceed 0.5mA to the adjacent terminal and ground of the mate connectors. 以測試用圓 Pin 針與插座嵌合, 於其相鄰兩導體末端各施以電壓 1000V A/C(實效值) 時間 1 分鐘, 且漏電流必須小於 0.5mA(毫安培) (EIA 364-20C)	No breakdown or flashover. 無損毀或者產生火花

8.0 Environmental Performance(環境性能) :

Item(項目)	Test Condition(測試條件)	Requirement(規格)
8.1 Humidity 恆溫恆濕	A mated (with 0.46 Diameter test pin)connector shall be placed in a humidity chamber of the following conditions. After the test, the contact resistance, the insulation resistance and the dielectric withstanding voltage shall be measured. (EIA 364-31B Conditions III . Method A) 以測試用圓 Pin 針與插座嵌合, 放置於恆定溫度的濕氣空間, 依照隨附如下規格要求, 進行恆溫恆濕試驗, 並於試驗過後量測其接觸阻抗、絕緣阻抗、以及耐電壓測試。 Temperature(溫度) : 40±2°C. Relative Humidity(相對濕度) : 90%~95% (RH). Period(週期) : 96 hours continuously. (持續 96 小時)	(After the test) Contact Resistance: 10milliohms Max. 經恆溫恆濕試驗後接觸阻抗 : 最大容許值. 10m 歐姆 (After the test) Insulation Resistance : 1000Megohms Min. 經恆溫恆濕試驗後絕緣阻抗 : 最小容許值. 1000M 歐姆 經恆溫恆濕試驗後測耐電壓 : (After the test) Withstanding Voltage: 1000V A/C for 1 minute



Type Document	Product Specification	Revised /Edition	D
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Item(項目)	Test Condition(測試條件)	Requirement(規格)
8.2 Thermal Shock 冷熱衝擊	<p>A mated (with 0.46 Diameter test pin)connector shall be subjected to a thermal shock test of the following conditions.</p> <p>After the test, the contact resistance, the insulation resistance and the dielectric withstanding voltage shall be measured. 以測試用圓Pin針與插座嵌合作為試驗樣品, 依照隨附如下規格要求, 進行冷熱衝擊試驗, 並於試驗過後量測其接觸阻抗、絕緣阻抗、以及耐電壓測試。</p> <p>One Cycle Consists Of: (EIA 364-31B Conditions III . Method A) -55°C -3/+0°C for 30 minutes. → Room Temp.5 minutes 85°C +3/-0°C for 30 minutes. → Room Temp.5 minutes</p> <p>Total Cycles: 5 Cycles. 以-55°C -3/+0°C溫度持續 30 分鐘, 經室溫 5 分鐘, 而後再以 85°C +3/-0°C溫度持續 30 分鐘, 再經室溫 5 分鐘, 構成一次冷熱循環, 總計循環次數 5 次。</p>	<p>Same as paragraph 8.1 同 8.1 章節</p>
8.3 Thermal Aging 高溫老化試驗	<p>A mated (with 0.46 Diameter test pin)connector shall be placed in a heat oven of the following conditions. After the test, contact resistance shall be measured.</p> <p>(EIA 364-17B Conditions III . Method A)</p> <p>以測試用圓 Pin 針與插座嵌合放置於加熱烤箱當中, 依照隨附如下規格要求, 進行高溫老化試驗, 並於試驗過後量測其接觸阻抗。</p> <p>Temperature(溫度): 85±2°C. Period(週期): 96 hours continuously . (持續 96 小時)</p>	<p>Initial Contact Resistance : 10 milliohms Max. 接觸阻抗最初容許值:10m 歐姆 (After the test) Contact Resistance : 20m Ω Max. . 經高溫老化試驗後接觸阻抗 : 最大容許值.20m 歐姆</p>
8.4 Salt Spray 鹽水噴霧	<p>A mated (with 0.46 Diameter test pin)connector shall be subjected to a Salt Spray test of the following conditions.</p> <p>After the test , the specimen shall be washed with running water and dried naturally before the measurement of contact resistance. (EIA 364-26B Conditions B)</p> <p>以測試用圓 Pin 針與插座嵌合作為試驗樣品, 依照隨附如下規格要求, 進行鹽水噴霧試驗, 試驗過後將樣品用清水沖洗並經過自然風乾, 而後量測其接觸阻抗。</p> <p>Density(鹽水密度): 5 % in weight. Temperature(溫度): 35±2°C. Period(週期): 48 hours</p>	<p>Initial Contact Resistance : 10 milliohms Max. 接觸阻抗最初容許值:10m 歐姆 (After the test) Contact Resistance: 20 milliohms Max. 經鹽水噴霧試驗後接觸阻抗 : 最大容許值. 20m 歐姆</p>



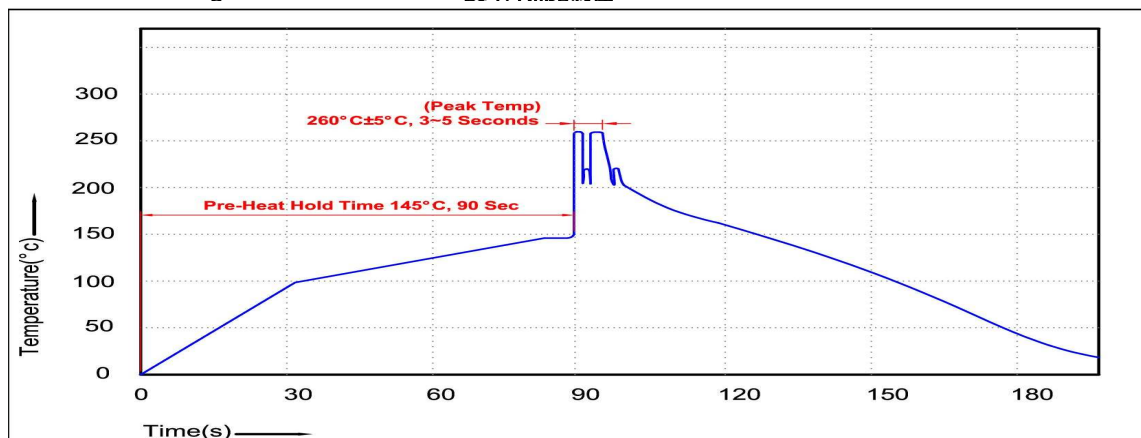
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Item(項目)	Test Condition(測試條件)	Requirement(規格)
8.5 Solder Ability 焊錫性	Fluxed soldering section of header shall be dipped in solder of the following conditions. 將連接器 pin 針基板嵌入端，接觸熱溶狀錫料，依照隨附如下規格要求，進行焊錫性試驗 (EIA 364-52B) Solder Temperature (焊錫溫度) : 245 ± 5°C. Immersion Period (沉浸週期) : 3 ±0.5 Seconds (操作方式) : 料件焊錫位置，距離導體末端 1.5mm Method : 1.5mm from contact tip	Solder entirely (Tin Plated : 95% / Gold Plated : 75%) of immersed area must show no voids or pinholes. 焊料覆蓋面積必須達到 (鍍錫 95% / 鍍金 75%)，而且不能產生氣孔或空隙
8.6 Resistance To Soldering Heat 焊錫耐熱性	By Wave Soldering(波峰焊適用溫度範圍) : Refer to Temperature Profile 請參考 8.6.1 溫度曲線圖 (EIA-364-71B) by soldering iron 手工烙鐵焊錫適用溫度範圍 : 350 ± 5°C 3±0.5 Seconds. (操作方式) : 料件焊錫位置，距離導體末端 1.5mm Method : 1.5mm from contact tip (EIA/ECA 364-56C Procedure 3. Conditions A)	No deformation or damage. 不可有變形或損壞

Notes : Flowing Mixed Gas (EIA 364-65A) shall be conduct by Customer request 混合流動氣體測試依照客戶需求

8.6.1 Temperature Profile(溫度曲線圖) :

Wave Peak Soldering In- Lead-Free Process 波峰焊無鉛制程 :



9.0 Remark(備註) : Any change or revision for the product specification will not be announced in advance.

Please contact our sales representative for the latest information.

有關規格書內容經變更或改版，如未能夠及時發佈與通知，煩請連絡我司業務人員以提供產品最新資訊

Reviewed: J.M.Chang **Approved:** Peter Chang **Verified:** Indiana Huang